

AMENDMENTS TO THE CLAIMS

1. (Original) A substrate plating apparatus for plating a substrate, comprising:
a plating unit including at least one plating chamber for containing a plating solution for plating a metal layer onto a semiconductor substrate;
a concentration analyzing device to analyze concentrations of the plating solution, wherein said concentration analyzing device includes a metal ion concentration analyzer and a plating additive concentration analyzer; and
a plating solution preparing unit for preparing the plating solution based on results from said concentration analyzing device.

Claims 2-5 (Cancelled)